



Material Content Data Sheet



Sales Product Name		TLE4699GM		Issued		1. August 2018		
MA#		MA001718798						
Package		PG-DSO-14-30		Weight*		143.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.837	1.98	1.98	19823	19823
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8434	
wire	non noble metal	copper	7440-50-8	49.007	34.25	35.14	342469	351430
	noble metal	gold	7440-57-5	0.192	0.13	0.13	1341	1341
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1204
encapsulation	plastics	epoxy resin	-	7.925	5.54		55383	
	inorganic material	silicondioxide	60676-86-0	78.046	54.55	60.21	545401	601988
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8569	8569
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7196	7196
glue	plastics	acrylic resin	-	0.304	0.21		2124	
	noble metal	silver	7440-22-4	1.077	0.75	0.96	7529	9653
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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